## **Amendments to the Claims**

This listing of claims will replace all prior versions and listings of claims in the above-identified application.

## **Listing of Claims**

1. (Previously Presented) A method comprising:

forming a tungsten plug in a dielectric layer;

- forming an electrically conductive interconnect line on the dielectric layer after formation of the tungsten plug, wherein the tungsten plug is electrically connected to the electrically conductive interconnect line;
- contacting the electrically conductive interconnect line with liquid water after formation of the electrically conductive interconnect line;
- contacting the electrically conductive interconnect line with a solution to remove residual polymer after the electrically conductive interconnect line is contacted with the liquid water;
- wherein the electrically conductive interconnect line is contacted with the liquid water for less than 120 minutes.
- 2. (Previously Presented) The method of claim 1 wherein the liquid water is degasified and deionized.
- 3. (Previously Presented) The method of claim 1 wherein the liquid water is deionized but not degasified.
- 4. (Previously Presented) The method of claim 1 wherein the liquid water is degasified but not deionized.
- 5. (Previously Presented) The method of claim 1 wherein the liquid water is neither degasified nor deionized.

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- 6. (Previously Presented) The method of claim 1 wherein the liquid water has a pH that is at or near neutral.
- 7. (Previously Presented) The method of claim 1 wherein the electrically conductive interconnect line is contacted with the liquid water for less than 60 minutes.
- 8. (Previously Presented) The method of claim 1 wherein the electrically conductive interconnect line is contacted with the liquid water for less than 15 minutes.
- 9. (Original) The method of claim 1 wherein the electrically conductive interconnect line is formed from a metal stack that includes one or more of titanium, titanium nitride, aluminum, an aluminum copper alloy, and an aluminum silicon copper alloy.

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10. - 26. (Canceled).

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